

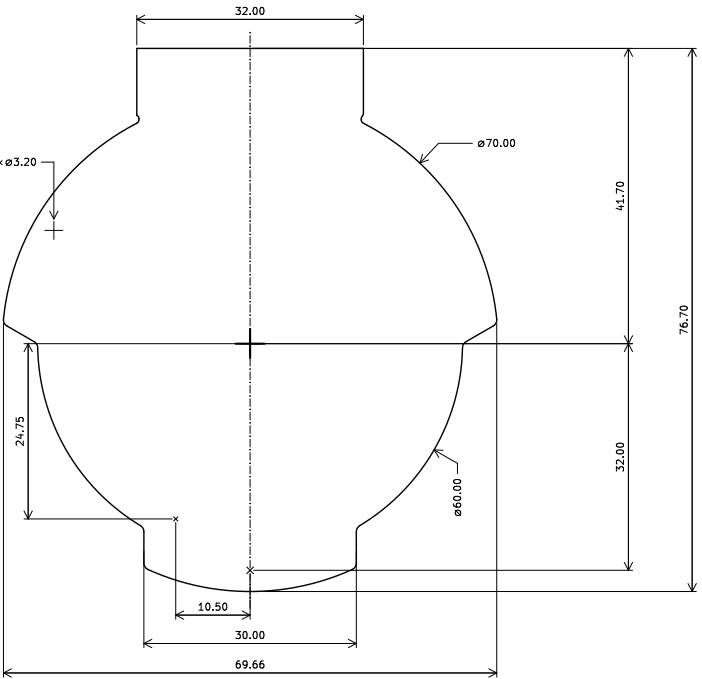
Top Fabrication (Scale 1:1)

Layer Stack Legend

	Material	Layer	Thickness	Dielectric Material	Type	Gerber
	F.Paste				Paste Mask	GBR
	F.Silkscreen				Legend	GBR
	F.Mask				Solder Mask	GBR
	Copper	L1 (Sig, PWR)	0.07mm (2oz)	Solder Resist	Signal	GBR
	Prepreg		0.18mm	FR-4	Dielectric	
	Copper	L2 (GND)	0.035mm (1oz)		Internal Plane	GBR
	Core		0.4mm	FR-4	Dielectric	
	Copper	L3 (Sig, PWR)	0.035mm (1oz)		Signal	GBR
	Prepreg		0.18mm	FR-4	Dielectric	
	Copper	L4 (Sig, PWR)	0.035mm (1oz)		Signal	GBR
	Core		0.4mm	FR-4	Dielectric	
	Copper	L5 (GND)	0.035mm (1oz)		Internal Plane	GBR
	Prepreg		0.18mm	FR-4	Dielectric	
	Copper	L6 (Sig, PWR)	0.07mm (2oz)		Signal	GBR
	B.Mask			Solder Resist	Solder Mask	GBR
	B.Silkscreen				Legend	GBR
	B.Paste				Paste Mask	GBR
Total thickness: 1.62mm						
Note: external layer thicknesses are specified after plating.						

FABRICATION NOTES (UNLESS OTHERWISE SPECIFIED)

- 1) OUTLINE DEFINED IN SEPARATE GERBER FILE WITH "Edge_Cuts.GBR" SUFFIX.
DIMENSIONS OF CIRCUMSIZED RECTANGLE SHOWN ON THIS DWG FOR REF ONLY.
- 2) SEE SEPARATE DRILL FILES WITH ".DRL" SUFFIX FOR HOLE LOCATIONS.
SELECTED HOLE LOCATIONS SHOWN ON THIS DWG FOR REF ONLY.
- 3) IMPEDANCE CONTROL REQUIRED.
Microstrip 100-Ohm Differential (L1 ref. L2)
0.2032mm width, 0.28mm spacing
- 4) CONFIRM TRACE WIDTHS AND SPACINGS.
- 5) DESIGN GEOMETRY MINIMUM FEATURE SIZES:
TRACE WIDTH 0.20 mm
TRACE TO TRACE 0.20 mm
MIN. HOLE (PTH) 0.25 mm
MIN. HOLE (NPTH) 0.70 mm
ANNULAR RING 0.15 mm
COPPER TO HOLE 0.254 mm
COPPER TO EDGE 0.25 mm
HOLE TO HOLE 0.254 mm



All dimensions are in millimeters unless otherwise specified.